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EIA STANDARD

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Surface Mount Ferrite Chip Bead Qualification Specification

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Electronic Components Industry Association

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Surface Mount Ferrite Chip Bead Qualification Specification

1 Scope

1.1 Description

This specification defines the qualification program for surface mount ferrite chip beads. The qualification program is defined in Table 1. Specification sheets can be added, as required, to define specific products or to cover unique/specific requirements. This document does not relieve the supplier of their responsibility to their own company's internal qualification program.

1.2 Reference documents

The current revision of the referenced documents will be in effect at the date of agreement to the qualification plan. Subsequent qualification plans will automatically use the latest revisions of these referenced documents:

MIL-STD-202	Test Method Standard - Electronic and Electrical Component Parts
MIL-HDBK-53-1A	Military Handbook - Guide for Attribute Lot Sampling Inspection
UL-94V	Tests for Flammability of Plastic Materials
IEC 60068	Basic Environmental Testing Procedures
IPC-9504 (Preconditioning)	Assembly Process Simulation for Evaluation of Non-IC Components

2 General Requirements

This specification includes requirements with the intention of developing a single set of robust qualification tests that would enable a supplier to leverage test results to satisfy the requirements of multiple original equipment manufacturer (OEM) customers.

2.1 Objective

The objective of this qualification program is to ensure that components meet a minimum quality and/or reliability level.

2.2 Generic data

2.2.1 The use of generic data to satisfy qualification requirements

The use of generic data for qualification will be based on specific requirements associated with each characteristic of the device and manufacturing process. These requirements, listed in Table 1, are the same for new components, new processes, and requalification associated with a process change. A maximum negotiable set of qualification tests must be performed for the appropriate changes proposed for the component or process. Section 2.2.2 *Qualification families* defines the criteria by which components are grouped into a qualification family for the purpose of considering the data from one or more components that can be generically applied to the